8-Stage Shift/Store Register with Three-State Outputs

The MC14094B combines an 8-stage shift register with a data latch for each stage and a 3-state output from each latch.

Data is shifted on the positive clock transition and is shifted from the seventh stage to two serial outputs. The Q_S output data is for use in high–speed cascaded systems. The Q_S output data is shifted on the following negative clock transition for use in low–speed cascaded systems.

Data from each stage of the shift register is latched on the negative transition of the strobe input. Data propagates through the latch while strobe is high.

Outputs of the eight data latches are controlled by 3-state buffers which are placed in the high-impedance state by a logic Low on Output Enable.

Features

- 3-State Outputs
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load Over the Rated Temperature Range
- Input Diode Protection
- Data Latch
- Dual Outputs for Data Out on Both Positive and Negative Clock Transitions
- Useful for Serial-to-Parallel Data Conversion
- Pin-for-Pin Compatible with CD4094B
- Pb-Free Packages are Available*

MAXIMUM RATINGS (Voltages Referenced to VSS)

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	-0.5 to +18.0	V
V _{in} , V _{out}	Input or Output Voltage Range (DC or Transient)	-0.5 to $V_{DD} + 0.5$	V
I _{in} , I _{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P _D	Power Dissipation, per Package (Note 1)	500	mW
T _A	Ambient Temperature Range	-55 to +125	°C
T _{stg}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.



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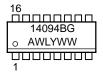
http://onsemi.com

MARKING DIAGRAMS



PDIP-16 P SUFFIX CASE 648 

SOIC-16 D SUFFIX CASE 751B



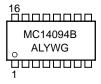


TSSOP-16 DT SUFFIX CASE 948F





SOEIAJ-16 F SUFFIX CASE 966



A = Assembly Location

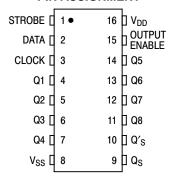
WL, L = Wafer Lot YY, Y = Year WW, W = Work Week G = Pb-Free Indicator

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PIN ASSIGNMENT



TRUTH TABLE

	Output		Parallel Outputs Serial Ou		Parallel Outputs		Outputs
Clock	Enable	Strobe	Data	Q1	Q _N	Q _S *	Q′ _S
	0	Х	Х	Z	Z	Q7	No Chg.
~	0	Х	Х	Z	Z	No Chg.	Q7
	1	0	Х	No Chg.	No Chg.	Q7	No Chg.
	1	1	0	0	Q _N -1	Q7	No Chg.
	1	1	1	1	Q _N -1	Q7	No Chg.
~	1	1	1	No Chg.	No Chg.	No Chg.	Q7

Z = High Impedance X = Don't Care

ORDERING INFORMATION

Device	Package	Shipping [†]
MC14094BCP	PDIP-16	500 Units / Rail
MC14094BCPG	PDIP-16 (Pb-Free)	500 Units / Rail
MC14094BD	SOIC-16	48 Units / Rail
MC14094BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14094BDR2	SOIC-16	2500 Units / Tape & Reel
MC14094BDR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
MC14094BDTR2	TSSOP-16*	2500 Units / Tape & Reel
MC14094BF	SOEIAJ-16	50 Units / Rail
MC14094BFG	SOEIAJ-16 50 Units / Rail (Pb-Free)	
MC14094BFEL	SOEIAJ-16	2000 Units / Tape & Reel
MC14094BFELG	SOEIAJ-16 (Pb-Free)	2000 Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. *This package is inherently Pb–Free.

^{*} At the positive clock edge, information in the 7th shift register stage is transferred to Q8 and Qs.

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

		V _{DD}	- 5	5°C		25°C		12	5°C	
Characteristic	Symbol	Vdc	Min	Max	Min	Typ ⁽²⁾	Max	Min	Max	Unit
Output Voltage "0" Le V _{in} = V _{DD} or 0	vel V _{OL}	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
"1" Le	vel V _{OH}	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- - -	Vdc
Input Voltage "0" Le $(V_O = 4.5 \text{ or } 0.5 \text{ Vdc})$ $(V_O = 9.0 \text{ or } 1.0 \text{ Vdc})$ $(V_O = 13.5 \text{ or } 1.5 \text{ Vdc})$	vel V _{IL}	5.0 10 15	- - -	1.5 3.0 4.0	- - -	2.25 4.50 6.75	1.5 3.0 4.0	- - -	1.5 3.0 4.0	Vdc
"1" Le $(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	vel V _{IH}	5.0 10 15	3.5 7.0 11	- - -	3.5 7.0 11	2.75 5.50 8.25	- - -	3.5 7.0 11	- - -	Vdc
Output Drive Current $ (V_{OH} = 2.5 \text{ Vdc}) $ Sou $ (V_{OH} = 4.6 \text{ Vdc}) $ $ (V_{OH} = 9.5 \text{ Vdc}) $ $ (V_{OH} = 13.5 \text{ Vdc}) $	ce I _{OH}	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	- - - -	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8	- - - -	- 1.7 - 0.36 - 0.9 - 2.4	- - - -	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ S $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	nk I _{OL}	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mAdc
Input Current	I _{in}	15	-	± 0.1	-	±0.00001	± 0.1	-	± 1.0	μAdc
Input Capacitance (V _{in} = 0)	C _{in}	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)	I _{DD}	5.0 10 15	- - -	5.0 10 20	- - -	0.005 0.010 0.015	5.0 10 20	- - -	150 300 600	μAdc
Total Supply Current ⁽³⁾ ⁽⁴⁾ (Dynamic plus Quiescent, Per Package) (C _L = 50 pF on all outputs, all buffers switching)	I _T	5.0 10 15			$I_T = ($	4.1 μΑ/kHz) f 14 μΑ/kHz) f 40 μΑ/kHz)	+ I _{DD}			μAdc
3-State Output Leakage Current	I _{TL}	15	_	± 0.1	-	± 0.0001	± 0.1	_	± 3.0	μΑ

^{2.} Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I_T is in μA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and k = 0.001.

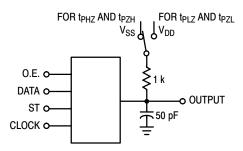
^{3.} The formulas given are for the typical characteristics only at 25°C.
4. To calculate total supply current at loads other than 50 pF:

SWITCHING CHARACTERISTICS (5) (C_L = 50 pF, T_A = 25°C)

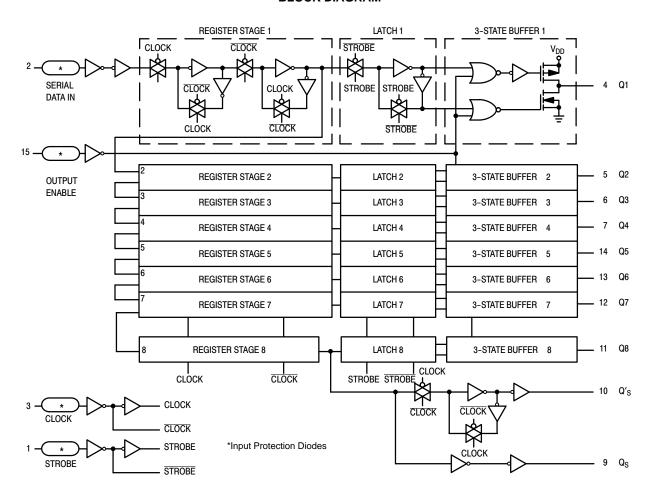
Characteristic	Symbol	V _{DD} Vdc	Min	Typ ⁽⁶⁾	Max	Unit
Output Rise and Fall Time t_{TLH} , t_{THL} = (1.35 ns/pF) C_L + 33 ns t_{TLH} , t_{THL} = (0.6 ns/pF) C_L + 20 ns t_{TLH} , t_{THL} = (0.4 ns/pF) C_L + 20 ns	t _{TLH} , t _{THL}	5.0 10 15	- - -	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Serial out QS t _{PLH} , t _{PHL} = (0.90 ns/pF) C _L + 305 ns t _{PLH} , t _{PHL} = (0.36 ns/pF) C _L + 107 ns t _{PLH} , t _{PHL} = (0.26 ns/pF) C L + 82 ns	t _{PLH} , t _{PHL}	5.0 10 15	- - -	350 125 95	600 250 190	ns
Clock to Serial out Q'S $t_{PLH}, t_{PHL} = (0.90 \text{ ns/pF}) \text{ C}_L + 350 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.36 \text{ ns/pF}) \text{ C}_L + 149 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.26 \text{ ns/pF}) \text{ C}_L + 62 \text{ ns}$		5.0 10 15	- - -	230 110 75	460 220 150	
Clock to Parallel out $t_{PLH},t_{PHL}=(0.90\;\text{ns/pF})\;C_L+375\;\text{ns}$ $t_{PLH},t_{PHL}=(0.35\;\text{ns/pF})\;C_L+177\;\text{ns}$ $t_{PLH},t_{PHL}=(0.26\;\text{ns/pF})\;C_L+122\;\text{ns}$		5.0 10 15	- - -	420 195 135	840 390 270	
Strobe to Parallel out $t_{PLH}, t_{PHL} = (0.90 \text{ ns/pF}) \text{ C}_{L} + 245 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.36 \text{ ns/pF}) \text{ C}_{L} + 127 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.26 \text{ ns/pF}) \text{ C}_{L} + 87 \text{ ns}$		5.0 10 15	- - -	290 145 100	580 290 200	
Output Enable to Output $ \begin{array}{l} t_{PHZ}, \ t_{PZL} = (0.90 \ \text{ns/pF}) \ \text{C}_{\text{L}} + 95 \ \text{ns} \\ t_{PHZ}, \ t_{PZL} = (0.36 \ \text{ns/PF}) \ \text{C}_{\text{L}} + 57 \ \text{ns} \\ t_{PHZ}, \ t_{PZL} = (0.26 \ \text{ns/pF}) \ \text{C}_{\text{L}} + 42 \ \text{ns} \end{array} $	t _{PHZ} , t _{PZL}	5.0 10 15	- - -	140 75 55	280 150 110	
t_{PLZ} , t_{PZH} = (0.90 ns/pF) C_L + 180 ns t_{PLZ} , t_{PZH} = (0.36 ns/pF) C_L + 77 ns t_{PLZ} , t_{PZH} = (0.26 ns/pF) C_L + 57 ns	t _{PLZ} , t _{PZH}	5.0 10 15	- - -	225 95 70	450 190 140	
Setup Time Data in to Clock	t _{su}	5.0 10 15	125 55 35	60 30 20	- - -	ns
Hold Time Clock to Data	t _h	5.0 10 15	0 20 20	- 40 - 10 0	- - -	ns
Clock Pulse Width, High	t _{WH}	5.0 10 15	200 100 83	100 50 40	- - -	ns
Clock Rise and Fall Time	$\begin{matrix} t_{r(\text{cl})} \\ t_{f(\text{cl})} \end{matrix}$	5 10 15		- - -	15 5.0 4.0	μS
Clock Pulse Frequency	f _{cl}	5.0 10 15	- - -	2.5 5.0 6.0	1.25 2.5 3.0	MHz
Strobe Pulse Width	t _{WL}	5.0 10 15	200 80 70	100 40 35	- - -	ns

^{5.} The formulas given are for the typical characteristics only at 25°C.6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

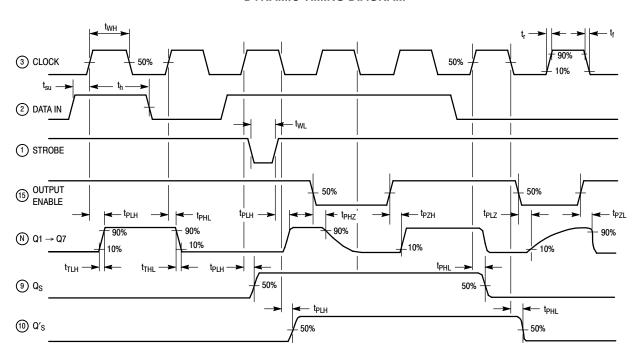
3-STATE TEST CIRCUIT



BLOCK DIAGRAM

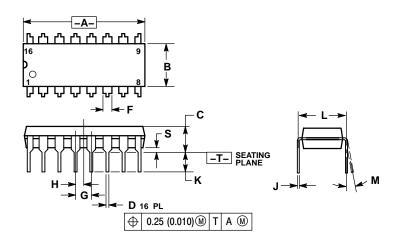


DYNAMIC TIMING DIAGRAM



PACKAGE DIMENSIONS

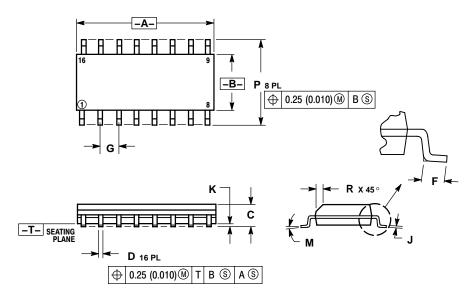
PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 **ISSUE T**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

SOIC-16 **D SUFFIX** PLASTIC SOIC PACKAGE CASE 751B-05 **ISSUE J**



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) DED SIDE.

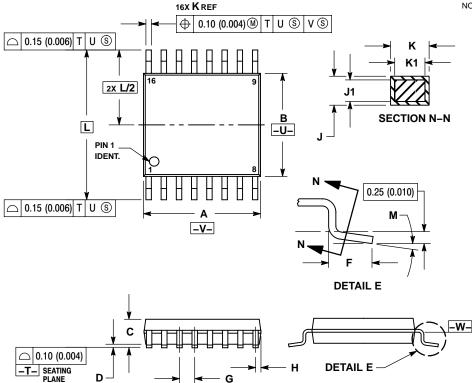
- PER SIDE.

 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT
 MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MIN MAX		MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0°	7°	0°	7°	
P	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

PACKAGE DIMENSIONS

TSSOP-16 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948F-01 **ISSUE A**



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR

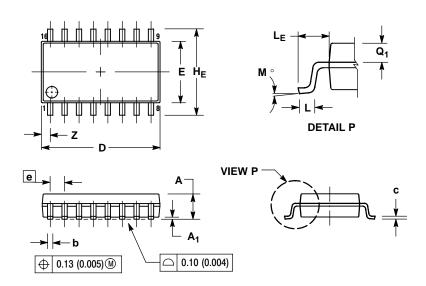
 - REFERENCE ONLY.

 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
C		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
Н	0.18	0.28	0.007	0.011
7	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252	
М	0°	8°	0°	8 °

PACKAGE DIMENSIONS

SOEIAJ-16 **F SUFFIX** PLASTIC EIAJ SOIC PACKAGE CASE 966-01 **ISSUE O**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (n 006) PER SIDE.

 - OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE 4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
p	0.35	0.50	0.014	0.020
C	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Ε	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050 BSC	
ΗE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
F	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10°
Q_1	0.70	0.90	0.028	0.035
Z		0.78		0.031

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